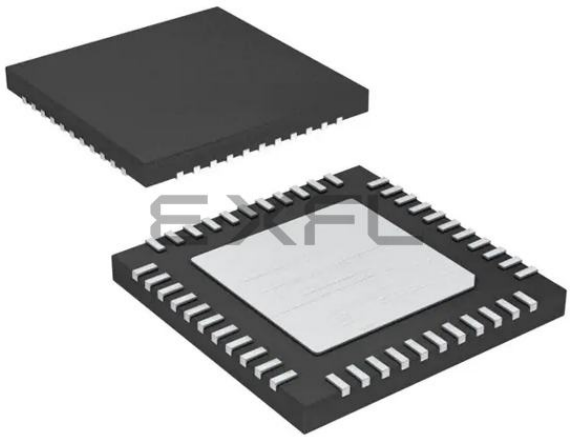
Microchip Technology - DSPIC33FJ128GP204T-I/ML Datasheet



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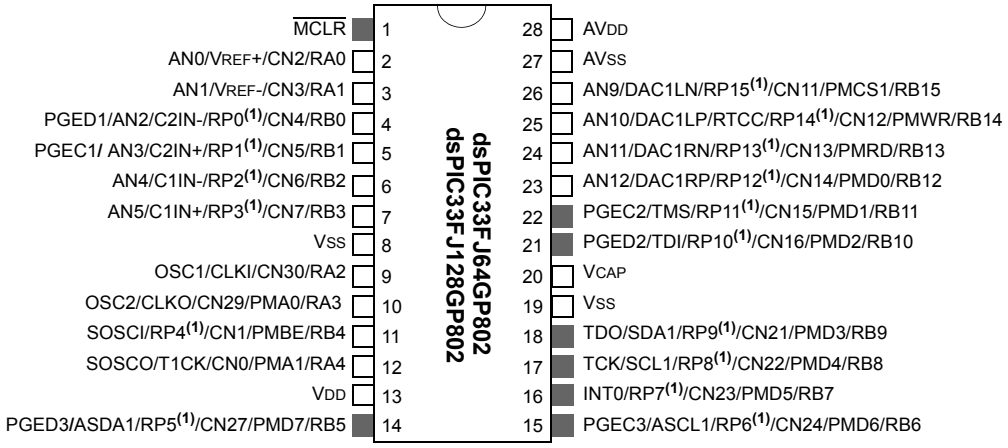
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	AC'97, Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 13x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj128gp204t-i-ml

Pin Diagrams

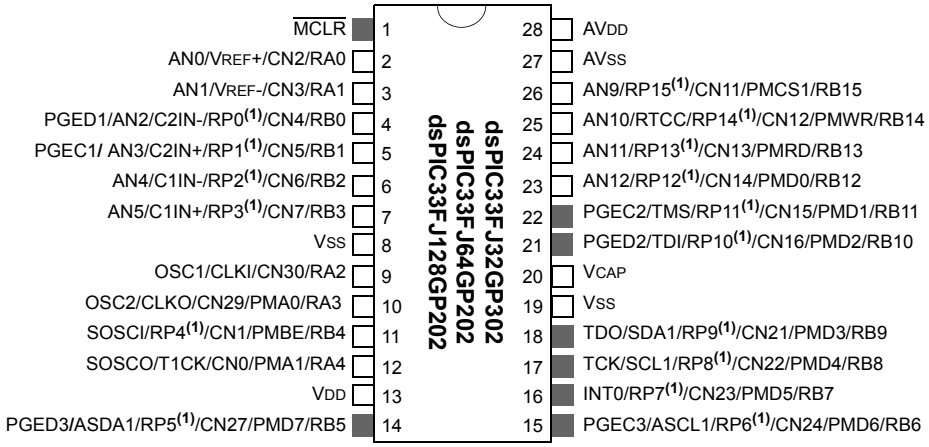
28-Pin SPDIP, SOIC

■ = Pins are up to 5V tolerant



28-Pin SPDIP, SOIC

■ = Pins are up to 5V tolerant



Note 1: The RPx pins can be used by any remappable peripheral. See Table 1 in this section for the list of available peripherals.

4.2 Data Address Space

The dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 CPU has a separate 16-bit-wide data memory space. The data space is accessed using separate Address Generation Units (AGUs) for read and write operations. The data memory maps is shown in Figure 4-4.

All Effective Addresses (EAs) in the data memory space are 16 bits wide and point to bytes within the data space. This arrangement gives a data space address range of 64 Kbytes or 32K words. The lower half of the data memory space (that is, when EA<15> = 0) is used for implemented memory addresses, while the upper half (EA<15> = 1) is reserved for the Program Space Visibility area (see **Section 4.8.3 "Reading Data from Program Memory Using Program Space Visibility"**).

dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 devices implement up to 16 Kbytes of data memory. Should an EA point to a location outside of this area, an all-zero word or byte is returned.

4.2.1 DATA SPACE WIDTH

The data memory space is organized in byte addressable, 16-bit wide blocks. Data is aligned in data memory and registers as 16-bit words, but all data space EAs resolve to bytes. The Least Significant Bytes (LSBs) of each word have even addresses, while the Most Significant Bytes (MSBs) have odd addresses.

4.2.2 DATA MEMORY ORGANIZATION AND ALIGNMENT

To maintain backward compatibility with PIC® MCU devices and improve data space memory usage efficiency, the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 instruction set supports both word and byte operations. As a consequence of byte accessibility, all effective address calculations are internally scaled to step through word-aligned memory. For example, the core recognizes that Post-Modified Register Indirect Addressing mode [Ws++] results in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

A data byte read, reads the complete word that contains the byte, using the LSB of any EA to determine which byte to select. The selected byte is placed onto the LSB of the data path. That is, data memory and registers are organized as two parallel byte-wide entities with shared (word) address decode but separate write lines. Data byte writes only write to the corresponding side of the array or register that matches the byte address.

All word accesses must be aligned to an even address. Misaligned word data fetches are not supported, so care must be taken when mixing byte and word operations, or translating from 8-bit MCU code. If a misaligned read or write is attempted, an address error trap is generated. If the error occurred on a read, the instruction underway is completed. If the error occurred on a write, the instruction is executed but the write does not occur. In either case, a trap is then executed, allowing the system and/or user application to examine the machine state prior to execution of the address Fault.

All byte loads into any W register are loaded into the Least Significant Byte. The Most Significant Byte is not modified.

A sign-extend instruction (SE) is provided to allow user applications to translate 8-bit signed data to 16-bit signed values. Alternatively, for 16-bit unsigned data, user applications can clear the MSB of any W register by executing a zero-extend (ZE) instruction on the appropriate address.

4.2.3 SFR SPACE

The first 2 Kbytes of the Near Data Space, from 0x0000 to 0x07FF, is primarily occupied by Special Function Registers (SFRs). These are used by the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 core and peripheral modules for controlling the operation of the device.

SFRs are distributed among the modules that they control, and are generally grouped together by module. Much of the SFR space contains unused addresses; these are read as '0'.

Note:	The actual set of peripheral features and interrupts varies by the device. Refer to the corresponding device tables and pinout diagrams for device-specific information.

4.2.4 NEAR DATA SPACE

The 8 Kbyte area between 0x0000 and 0x1FFF is referred to as the near data space. Locations in this space are directly addressable via a 13-bit absolute address field within all memory direct instructions. Additionally, the whole data space is addressable using MOV instructions, which support Memory Direct Addressing mode with a 16-bit address field, or by using Indirect Addressing mode using a working register as an address pointer.

TABLE 4-1: CPU CORE REGISTERS MAP (CONTINUED)

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
MODCON	0046	XMODEN	YMODEN	—	—	BWM<3:0>				YWM<3:0>				XWM<3:0>				0000
XMODSRT	0048	XS<15:1>															0	xxxx
XMODEND	004A	XE<15:1>															1	xxxx
YMODSRT	004C	YS<15:1>															0	xxxx
YMODEND	004E	YE<15:1>															1	xxxx
XBREV	0050	BREN	XB<14:0>															xxxx
DISICNT	0052	—	—	Disable Interrupts Counter Register														xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-4: INTERRUPT CONTROLLER REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
INTCON1	0080	NSTDIS	OVAERR	OVBERR	COVAERR	COVBERR	OVATE	OVBTE	COVTE	SFTACERR	DIV0ERR	DMACERR	MATHERR	ADDRERR	STKERR	OSCFAIL	—	0000
INTCON2	0082	ALTIVT	DISI	—	—	—	—	—	—	—	—	—	—	—	INT2EP	INT1EP	INT0EP	0000
IFS0	0084	—	DMA1IF	AD1IF	U1TXIF	U1RXIF	SPI1IF	SPI1EIF	T3IF	T2IF	OC2IF	IC2IF	DMA0IF	T1IF	OC1IF	IC1IF	INT0IF	0000
IFS1	0086	U2TXIF	U2RXIF	INT2IF	T5IF	T4IF	OC4IF	OC3IF	DMA2IF	IC8IF	IC7IF	—	INT1IF	CNIF	CMIF	MI2C1IF	SI2C1IF	0000
IFS2	0088	—	DMA4IF	PMPIF	—	—	—	—	—	—	—	—	DMA3IF	C1IF(1)	C1RXIF(1)	SPI2IF	SPI2EIF	0000
IFS3	008A	—	RTCIF	DMA5IF	DCIIF	DCIEIF	—	—	—	—	—	—	—	—	—	—	—	0000
IFS4	008C	DAC1LIF(2)	DAC1RIF(2)	—	—	—	—	—	—	—	C1TXIF(1)	DMA7IF	DMA6IF	CRCIF	U2EIF	U1EIF	—	0000
IEC0	0094	—	DMA1IE	AD1IE	U1TXIE	U1RXIE	SPI1IE	SPI1EIE	T3IE	T2IE	OC2IE	IC2IE	DMA0IE	T1IE	OC1IE	IC1IE	INT0IE	0000
IEC1	0096	U2TXIE	U2RXIE	INT2IE	T5IE	T4IE	OC4IE	OC3IE	DMA2IE	IC8IE	IC7IE	—	INT1IE	CNIE	CMIE	MI2C1IE	SI2C1IE	0000
IEC2	0098	—	DMA4IE	PMPIE	—	—	—	—	—	—	—	—	DMA3IE	C1IE(1)	C1RXIE(1)	SPI2IE	SPI2EIE	0000
IEC3	009A	—	RTCIE	DMA5IE	DCIIE	DCIEIE	—	—	—	—	—	—	—	—	—	—	—	0000
IEC4	009C	DAC1LIE(2)	DAC1RIE(2)	—	—	—	—	—	—	—	C1TXIE(1)	DMA7IE	DMA6IE	CRCIE	U2EIE	U1EIE	—	0000
IPC0	00A4	—	T1IP<2:0>			—	OC1IP<2:0>			—	IC1IP<2:0>			—	INT0IP<2:0>			4444
IPC1	00A6	—	T2IP<2:0>			—	OC2IP<2:0>			—	IC2IP<2:0>			—	DMA0IP<2:0>			4444
IPC2	00A8	—	U1RXIP<2:0>			—	SPI1IP<2:0>			—	SPI1EIP<2:0>			—	T3IP<2:0>			4444
IPC3	00AA	—	—	—	—	—	DMA1IP<2:0>			—	AD1IP<2:0>			—	U1TXIP<2:0>			0444
IPC4	00AC	—	CNIP<2:0>			—	CMIP<2:0>			—	MI2C1IP<2:0>			—	SI2C1IP<2:0>			4444
IPC5	00AE	—	IC8IP<2:0>			—	IC7IP<2:0>			—	—	—	—	—	INT1IP<2:0>			4404
IPC6	00B0	—	T4IP<2:0>			—	OC4IP<2:0>			—	OC3IP<2:0>			—	DMA2IP<2:0>			4444
IPC7	00B2	—	U2TXIP<2:0>			—	U2RXIP<2:0>			—	INT2IP<2:0>			—	T5IP<2:0>			4444
IPC8	00B4	—	C1IP<2:0>(1)			—	C1RXIP<2:0>(1)			—	SPI2IP<2:0>			—	SPI2EIP<2:0>			4444
IPC9	00B6	—	—	—	—	—	—	—	—	—	—	—	—	—	DMA3IP<2:0>			0004
IPC11	00BA	—	—	—	—	—	DMA4IP<2:0>			—	PMPIP<2:0>			—	—	—	—	0440
IPC14	00C0	—	DCIEIP<2:0>			—	—	—	—	—	—	—	—	—	—	—	—	4000
IPC15	00C2	—	—	—	—	—	RTCIP<2:0>			—	DMA5IP<2:0>			—	DCIIP<2:0>			0444
IPC16	00C4	—	CRCIP<2:0>			—	U2EIP<2:0>			—	U1EIP<2:0>			—	—	—	—	4440
IPC17	00C6	—	—	—	—	—	C1TXIP<2:0>(1)			—	DMA7IP<2:0>			—	DMA6IP<2:0>			0444
IPC19	00CA	—	DAC1LIP<2:0>(2)			—	DAC1RIP<2:0>(2)			—	—	—	—	—	—	—	—	4400
INTTREG	00E0	—	—	—	—	ILR<3:0>>				—	VECNUM<6:0>							4444

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Interrupts disabled on devices without ECAN™ modules.

2: Interrupts disabled on devices without Audio DAC modules.

6.0 RESETS

Note 1: This data sheet summarizes the features of the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 8. "Reset"** (DS70192) of the "*dsPIC33F/PIC24H Family Reference Manual*", which is available from the Microchip website (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Reset module combines all reset sources and controls the device Master Reset Signal, $\overline{\text{SYSRST}}$. The following is a list of device Reset sources:

- POR: Power-on Reset
- BOR: Brown-out Reset
- $\overline{\text{MCLR}}$: Master Clear Pin Reset
- SWR: RESET Instruction
- WDTO: Watchdog Timer Reset
- CM: Configuration Mismatch Reset
- TRAPR: Trap Conflict Reset
- IOPUWR: Illegal Condition Device Reset
  - Illegal Opcode Reset
  - Uninitialized W Register Reset
  - Security Reset

A simplified block diagram of the Reset module is shown in Figure 6-1.

Any active source of reset will make the $\overline{\text{SYSRST}}$ signal active. On system Reset, some of the registers associated with the CPU and peripherals are forced to a known Reset state and some are unaffected.

Note: Refer to the specific peripheral section or **Section 3.0 "CPU"** of this manual for register Reset states.

All types of device Reset sets a corresponding status bit in the RCON register to indicate the type of Reset (see Register 6-1).

A POR clears all the bits, except for the POR bit (RCON<0>), that are set. The user application can set or clear any bit at any time during code execution. The RCON bits only serve as status bits. Setting a particular Reset status bit in software does not cause a device Reset to occur.

The RCON register also has other bits associated with the Watchdog Timer and device power-saving states. The function of these bits is discussed in other sections of this manual.

Note: The status bits in the RCON register should be cleared after they are read so that the next RCON register value after a device Reset is meaningful.

FIGURE 6-1: RESET SYSTEM BLOCK DIAGRAM

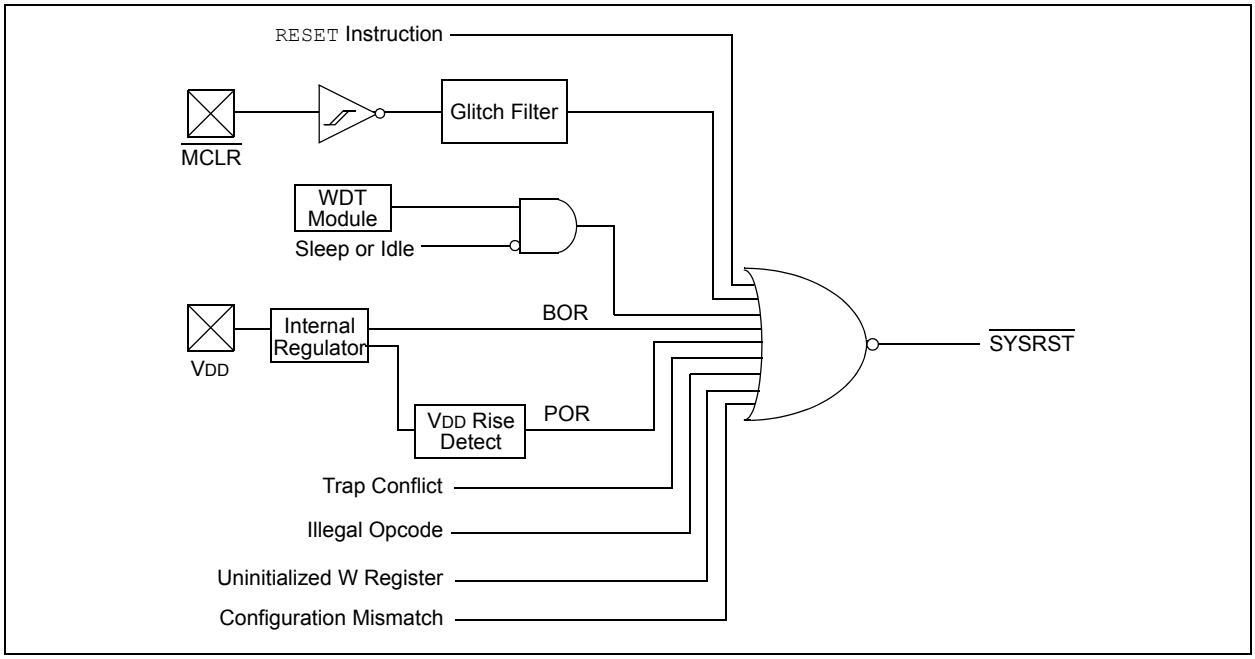


TABLE 7-1: INTERRUPT VECTORS

Vector Number	IVT Address	AIVT Address	Interrupt Source
0	0x000004	0x000104	Reserved
1	0x000006	0x000106	Oscillator Failure
2	0x000008	0x000108	Address Error
3	0x00000A	0x00010A	Stack Error
4	0x00000C	0x00010C	Math Error
5	0x00000E	0x00010E	DMA Error
6-7	0x000010-0x000012	0x000110-0x000112	Reserved
8	0x000014	0x000114	INT0 – External Interrupt 0
9	0x000016	0x000116	IC1 – Input Capture 1
10	0x000018	0x000118	OC1 – Output Compare 1
11	0x00001A	0x00011A	T1 – Timer1
12	0x00001C	0x00011C	DMA0 – DMA Channel 0
13	0x00001E	0x00011E	IC2 – Input Capture 2
14	0x000020	0x000120	OC2 – Output Compare 2
15	0x000022	0x000122	T2 – Timer2
16	0x000024	0x000124	T3 – Timer3
17	0x000026	0x000126	SPI1E – SPI1 Error
18	0x000028	0x000128	SPI1 – SPI1 Transfer Done
19	0x00002A	0x00012A	U1RX – UART1 Receiver
20	0x00002C	0x00012C	U1TX – UART1 Transmitter
21	0x00002E	0x00012E	ADC1 – ADC 1
22	0x000030	0x000130	DMA1 – DMA Channel 1
23	0x000032	0x000132	Reserved
24	0x000034	0x000134	SI2C1 – I2C1 Slave Events
25	0x000036	0x000136	MI2C1 – I2C1 Master Events
26	0x000038	0x000138	CM – Comparator Interrupt
27	0x00003A	0x00013A	CN – Change Notification Interrupt
28	0x00003C	0x00013C	INT1 – External Interrupt 1
29	0x00003E	0x00013E	Reserved
30	0x000040	0x000140	IC7 – Input Capture 7
31	0x000042	0x000142	IC8 – Input Capture 8
32	0x000044	0x000144	DMA2 – DMA Channel 2
33	0x000046	0x000146	OC3 – Output Compare 3
34	0x000048	0x000148	OC4 – Output Compare 4
35	0x00004A	0x00014A	T4 – Timer4
36	0x00004C	0x00014C	T5 – Timer5
37	0x00004E	0x00014E	INT2 – External Interrupt 2
38	0x000050	0x000150	U2RX – UART2 Receiver
39	0x000052	0x000152	U2TX – UART2 Transmitter
40	0x000054	0x000154	SPI2E – SPI2 Error
41	0x000056	0x000156	SPI2 – SPI2 Transfer Done
42	0x000058	0x000158	C1RX – ECAN1 RX Data Ready
43	0x00005A	0x00015A	C1 – ECAN1 Event
44	0x00005C	0x00015C	DMA3 – DMA Channel 3
45-52	0x00005E-0x00006C	0x00015E-0x00016C	Reserved
53	0x00006E	0x00016E	PMP – Parallel Master Port
54	0x000070	0x000170	DMA – DMA Channel 4

REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1 (CONTINUED)

bit 3 **ADDRERR:** Address Error Trap Status bit
1 = Address error trap has occurred
0 = Address error trap has not occurred

bit 2 **STKERR:** Stack Error Trap Status bit
1 = Stack error trap has occurred
0 = Stack error trap has not occurred

bit 1 **OSCFAIL:** Oscillator Failure Trap Status bit
1 = Oscillator failure trap has occurred
0 = Oscillator failure trap has not occurred

bit 0 **Unimplemented:** Read as '0'

REGISTER 7-22: IPC7: INTERRUPT PRIORITY CONTROL REGISTER 7

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	U2TXIP<2:0>			—	U2RXIP<2:0>		
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	INT2IP<2:0>			—	T5IP<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **U2TXIP<2:0>:** UART2 Transmitter Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **U2RXIP<2:0>:** UART2 Receiver Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **INT2IP<2:0>:** External Interrupt 2 Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **T5IP<2:0>:** Timer5 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

REGISTER 8-2: DMAxREQ: DMA CHANNEL x IRQ SELECT REGISTER

R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
FORCE(1)	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	IRQSEL6<6:0>(2)						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **FORCE:** Force DMA Transfer bit(1)
1 = Force a single DMA transfer (Manual mode)
0 = Automatic DMA transfer initiation by DMA request

bit 14-7 **Unimplemented:** Read as '0'

bit 6-0 **IRQSEL<6:0>:** DMA Peripheral IRQ Number Select bits(2)
1111111 = DMAIRQ127 selected to be Channel DMAREQ
.
.
.
0000000 = DMAIRQ0 selected to be Channel DMAREQ

Note 1: The FORCE bit cannot be cleared by the user. The FORCE bit is cleared by hardware when the forced DMA transfer is complete.

2: Refer to Table 7-1 for a complete listing of IRQ numbers for all interrupt sources.

REGISTER 8-7: DMACS0: DMA CONTROLLER STATUS REGISTER 0 (CONTINUED)

bit 3 **XWCOL3:** Channel 3 DMA RAM Write Collision Flag bit
1 = Write collision detected
0 = No write collision detected

bit 2 **XWCOL2:** Channel 2 DMA RAM Write Collision Flag bit
1 = Write collision detected
0 = No write collision detected

bit 1 **XWCOL1:** Channel 1 DMA RAM Write Collision Flag bit
1 = Write collision detected
0 = No write collision detected

bit 0 **XWCOL0:** Channel 0 DMA RAM Write Collision Flag bit
1 = Write collision detected
0 = No write collision detected

NOTES:

20.3 DCI Control Registers

REGISTER 20-1: DCICON1: DCI CONTROL REGISTER 1

R/W-0	U-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
DCIEN	—	DCISIDL	—	DLOOP	CSCKD	CSCKE	COFSD
bit 15							bit 8

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0
UNFM	CSDOM	DJST	—	—	—	COFSM<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **DCIEN:** DCI Module Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **DCISIDL:** DCI Stop in Idle Control bit
1 = Module will halt in CPU Idle mode
0 = Module will continue to operate in CPU Idle mode

bit 12 **Unimplemented:** Read as '0'

bit 11 **DLOOP:** Digital Loopback Mode Control bit
1 = Digital Loopback mode is enabled. CSDI and CSDO pins internally connected.
0 = Digital Loopback mode is disabled

bit 10 **CSCKD:** Sample Clock Direction Control bit
1 = CSCK pin is an input when DCI module is enabled
0 = CSCK pin is an output when DCI module is enabled

bit 9 **CSCKE:** Sample Clock Edge Control bit
1 = Data changes on serial clock falling edge, sampled on serial clock rising edge
0 = Data changes on serial clock rising edge, sampled on serial clock falling edge

bit 8 **COFSD:** Frame Synchronization Direction Control bit
1 = COFS pin is an input when DCI module is enabled
0 = COFS pin is an output when DCI module is enabled

bit 7 **UNFM:** Underflow Mode bit
1 = Transmit last value written to the transmit registers on a transmit underflow
0 = Transmit '0's on a transmit underflow

bit 6 **CSDOM:** Serial Data Output Mode bit
1 = CSDO pin will be tri-stated during disabled transmit time slots
0 = CSDO pin drives '0's during disabled transmit time slots

bit 5 **DJST:** DCI Data Justification Control bit
1 = Data transmission/reception is begun during the same serial clock cycle as the frame synchronization pulse
0 = Data transmission/reception is begun one serial clock cycle after frame synchronization pulse

bit 4-2 **Unimplemented:** Read as '0'

bit 1-0 **COFSM<1:0>:** Frame Sync Mode bits
11 = 20-bit AC-Link mode
10 = 16-bit AC-Link mode
01 = I^2S Frame Sync mode
00 = Multi-Channel Frame Sync mode

NOTES:

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
48	MPY	MPY Wm*Wn,Acc,Wx,Wxd,Wy,Wyd	Multiply Wm by Wn to Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
		MPY Wm*Wm,Acc,Wx,Wxd,Wy,Wyd	Square Wm to Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
49	MPY.N	MPY.N Wm*Wn,Acc,Wx,Wxd,Wy,Wyd	-(Multiply Wm by Wn) to Accumulator	1	1	None
50	MSC	MSC Wm*Wm,Acc,Wx,Wxd,Wy,Wyd, AWB	Multiply and Subtract from Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
51	MUL	MUL.SS Wb,Ws,Wnd	{Wnd + 1, Wnd} = signed(Wb) * signed(Ws)	1	1	None
		MUL.SU Wb,Ws,Wnd	{Wnd + 1, Wnd} = signed(Wb) * unsigned(Ws)	1	1	None
		MUL.US Wb,Ws,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * signed(Ws)	1	1	None
		MUL.UU Wb,Ws,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(Ws)	1	1	None
		MUL.SU Wb,#lit5,Wnd	{Wnd + 1, Wnd} = signed(Wb) * unsigned(lit5)	1	1	None
		MUL.UU Wb,#lit5,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(lit5)	1	1	None
		MUL f	W3:W2 = f * WREG	1	1	None
52	NEG	NEG Acc	Negate Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
		NEG f	f = $\bar{f}$ + 1	1	1	C,DC,N,OV,Z
		NEG f,WREG	WREG = $\bar{f}$ + 1	1	1	C,DC,N,OV,Z
		NEG Ws,Wd	Wd = $\overline{Ws}$ + 1	1	1	C,DC,N,OV,Z
53	NOP	NOP	No Operation	1	1	None
		NOPR	No Operation	1	1	None
54	POP	POP f	Pop f from Top-of-Stack (TOS)	1	1	None
		POP Wdo	Pop from Top-of-Stack (TOS) to Wdo	1	1	None
		POP.D Wnd	Pop from Top-of-Stack (TOS) to W(nd):W(nd + 1)	1	2	None
		POP.S	Pop Shadow Registers	1	1	All
55	PUSH	PUSH f	Push f to Top-of-Stack (TOS)	1	1	None
		PUSH Wso	Push Wso to Top-of-Stack (TOS)	1	1	None
		PUSH.D Wns	Push W(ns):W(ns + 1) to Top-of-Stack (TOS)	1	2	None
		PUSH.S	Push Shadow Registers	1	1	None
56	PWRSAV	PWRSAV #lit1	Go into Sleep or Idle mode	1	1	WDTO,Sleep
57	RCALL	RCALL Expr	Relative Call	1	2	None
		RCALL Wn	Computed Call	1	2	None
58	REPEAT	REPEAT #lit14	Repeat Next Instruction lit14 + 1 times	1	1	None
		REPEAT Wn	Repeat Next Instruction (Wn) + 1 times	1	1	None
59	RESET	RESET	Software device Reset	1	1	None
60	RETFIE	RETFIE	Return from interrupt	1	3 (2)	None
61	RETLW	RETLW #lit10,Wn	Return with literal in Wn	1	3 (2)	None
62	RETURN	RETURN	Return from Subroutine	1	3 (2)	None
63	RLC	RLC f	f = Rotate Left through Carry f	1	1	C,N,Z
		RLC f,WREG	WREG = Rotate Left through Carry f	1	1	C,N,Z
		RLC Ws,Wd	Wd = Rotate Left through Carry Ws	1	1	C,N,Z
64	RLNC	RLNC f	f = Rotate Left (No Carry) f	1	1	N,Z
		RLNC f,WREG	WREG = Rotate Left (No Carry) f	1	1	N,Z
		RLNC Ws,Wd	Wd = Rotate Left (No Carry) Ws	1	1	N,Z
65	RRC	RRC f	f = Rotate Right through Carry f	1	1	C,N,Z
		RRC f,WREG	WREG = Rotate Right through Carry f	1	1	C,N,Z
		RRC Ws,Wd	Wd = Rotate Right through Carry Ws	1	1	C,N,Z

30.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 electrical characteristics. Additional information is provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 family are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +160°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to V_{SS}(4) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} \geq 3.0V$(4) ..... -0.3V to +5.6V
Voltage on any 5V tolerant pin with respect to Vss when $V_{DD} < 3.0V$(4) ..... -0.3V to 3.6V
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin(2) ..... 250 mA
Maximum current sourced/sunk by any 2x I/O pin(3) ..... 8 mA
Maximum current sourced/sunk by any 4x I/O pin(3) ..... 15 mA
Maximum current sourced/sunk by any 8x I/O pin(3) ..... 25 mA
Maximum current sunk by all ports ..... 200 mA
Maximum current sourced by all ports(2) ..... 200 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” can cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 30-2).

3: Exceptions are CLKOUT, which is able to sink/source 25 mA, and the V_{REF}+, V_{REF}-, SCLx, SDAx, PGECx and PGEDx pins, which are able to sink/source 12 mA.

4: See the **“Pin Diagrams”** section for 5V tolerant pins.

TABLE 30-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.(3)	**Typical(2)**	**Max**	**Units**	**Conditions**		
Power-Down Current (I_{PD})(1)						
DC60d	24	68	µA	-40°C	3.3V	Base Power-Down Current(3,4)
DC60a	28	87	µA	+25°C		
DC60b	124	292	µA	+85°C		
DC60c	350	1000	µA	+125°C		
DC61d	8	13	µA	-40°C	3.3V	Watchdog Timer Current: ΔI_{WDT}(3,5)
DC61a	10	15	µA	+25°C		
DC61b	12	20	µA	+85°C		
DC61c	13	25	µA	+125°C		

Note 1: I_{PD} (Sleep) current is measured as follows:

- CPU core is off (i.e., Sleep mode), oscillator is configured in EC mode and external clock active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration word
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}, WDT and FSCM are disabled, all peripheral modules are disabled (PMDx bits are all '1's)
- RTCC is disabled
- JTAG is disabled

2: Data in the "Typ" column is at 3.3V, +25ºC unless otherwise stated.

3: The Watchdog Timer Current is the additional current consumed when the WDT module is enabled. This current should be added to the base I_{PD} current.

4: These currents are measured on the device containing the most memory in this family.

5: These parameters are characterized, but are not tested in manufacturing.

TABLE 30-17: PLL CLOCK TIMING SPECIFICATIONS (V_{DD} = 3.0V TO 3.6V)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
OS50	FPLLI	PLL Voltage Controlled Oscillator (VCO) Input Frequency Range	0.8	—	8	MHz	ECPLL, HSPLL, XTPLL modes
OS51	FSYS	On-Chip VCO System Frequency	100	—	200	MHz	—
OS52	TLOCK	PLL Start-up Time (Lock Time)	0.9	1.5	3.1	mS	—
OS53	DCLK	CLKO Stability (Jitter)(2)	-3	0.5	3	%	Measured over 100 ms period

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: These parameters are characterized by similarity, but are not tested in manufacturing. This specification is based on clock cycle by clock cycle measurements. To calculate the effective jitter for individual time bases or communication clocks use this formula:

$$Peripheral\ Clock\ Jitter = \frac{DCLK}{\sqrt{\left(\frac{FOSC}{Peripheral\ Bit\ Rate\ Clock}\right)}}$$

For example: Fosc = 32 MHz, DCLK = 3%, SPI bit rate clock, (i.e., SCK) is 2 MHz.

$$SPI\ SCK\ Jitter = \left[\frac{DCLK}{\sqrt{\left(\frac{32\ MHz}{2\ MHz}\right)}}\right] = \left[\frac{3\%}{\sqrt{16}}\right] = \left[\frac{3\%}{4}\right] = 0.75\%$$

TABLE 30-18: AC CHARACTERISTICS: INTERNAL RC ACCURACY

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**	
	Internal FRC Accuracy @ 7.3728 MHz(1)						
F20a	FRC	-2	—	+2	%	-40°C ≤ TA ≤ +85°C	VDD = 3.0-3.6V
F20b	FRC	-5	—	+5	%	-40°C ≤ TA ≤ +125°C	VDD = 3.0-3.6V

Note 1: Frequency calibrated at 25°C and 3.3V. TUN bits can be used to compensate for temperature drift.

TABLE 30-19: INTERNAL RC ACCURACY

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**	
	LPRC @ 32.768 kHz(1)						
F21a	LPRC	-20	±6	+20	%	-40°C ≤ TA ≤ +85°C	VDD = 3.0-3.6V
F21b	LPRC	-30	—	+30	%	-40°C ≤ TA ≤ +125°C	VDD = 3.0-3.6V

Note 1: Change of LPRC frequency as VDD changes.

32.0 DC AND AC DEVICE CHARACTERISTICS GRAPHS

Note: The graphs provided following this note are a statistical summary based on a limited number of samples and are provided for design guidance purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

FIGURE 32-1: VOH – 2x DRIVER PINS

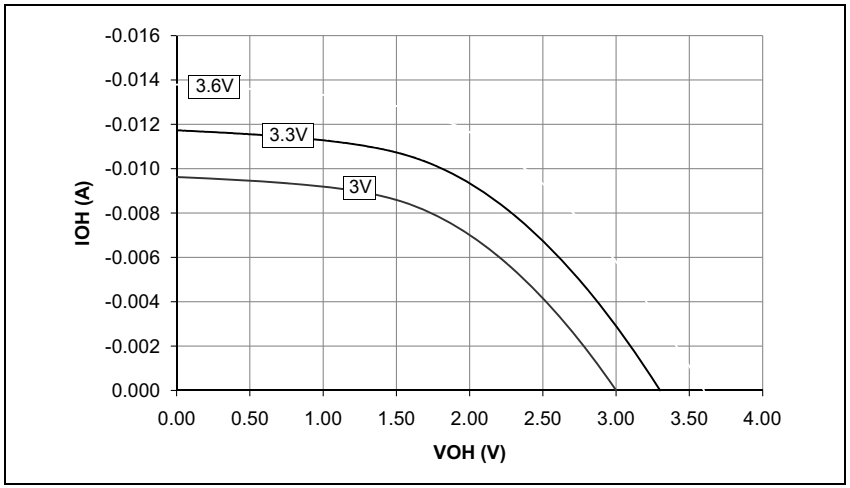


FIGURE 32-2: VOH – 4x DRIVER PINS

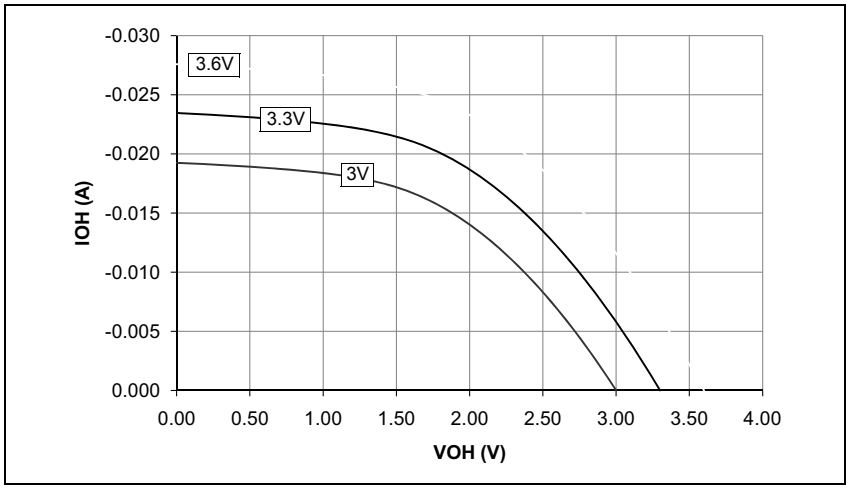


FIGURE 32-3: VOH – 8x DRIVER PINS

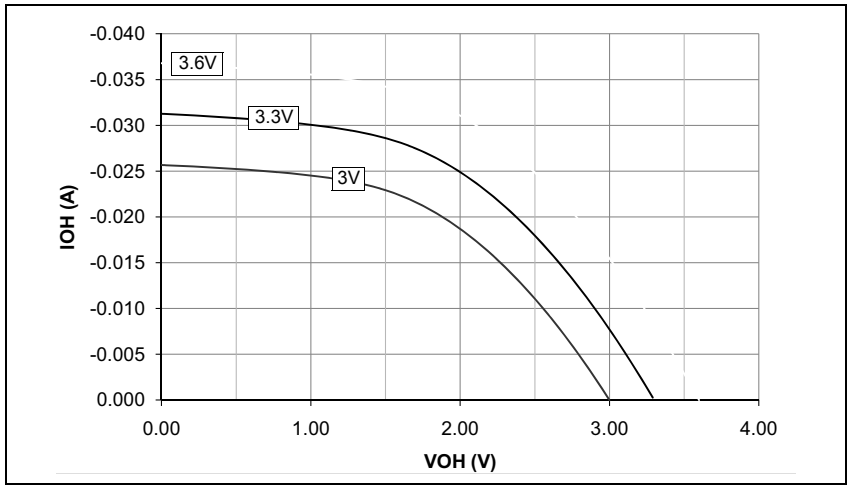
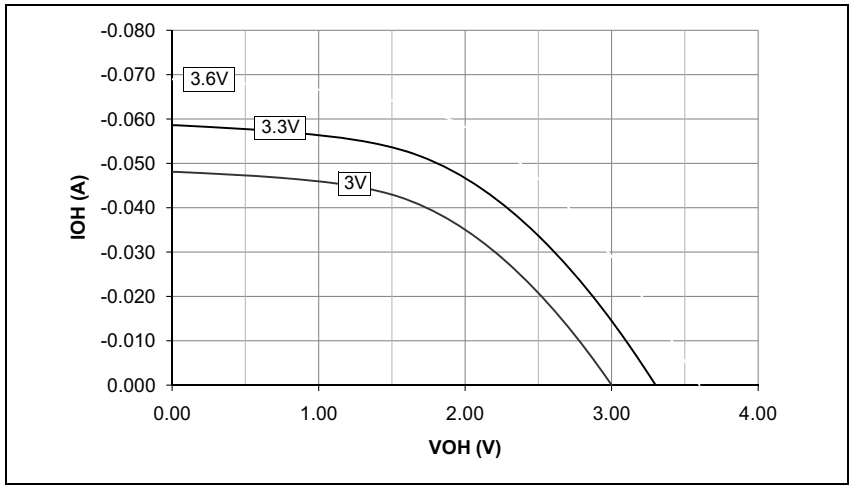
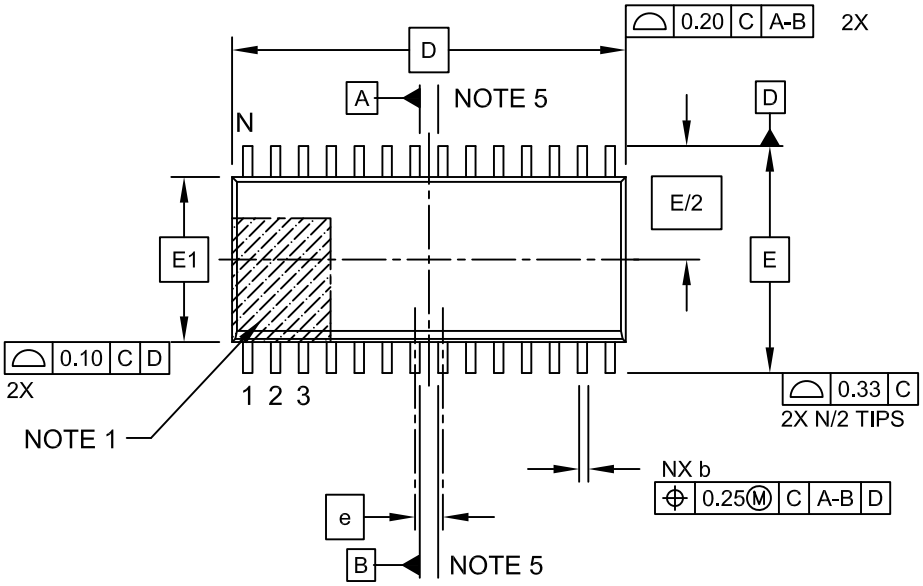


FIGURE 32-4: VOH – 16x DRIVER PINS

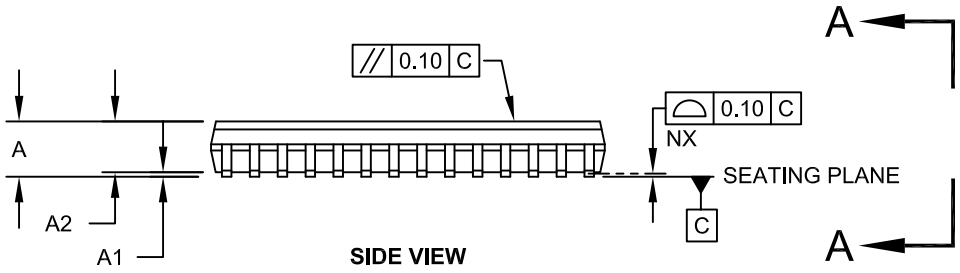


28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

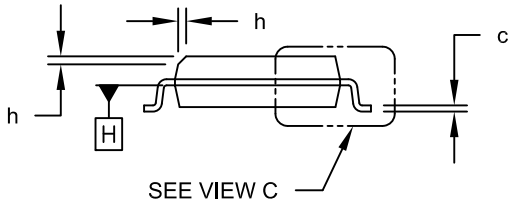
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW



VIEW A-A

Microchip Technology Drawing C04-052C Sheet 1 of 2

TABLE A-4: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 "Electrical Characteristics"	Updated the maximum value for Extended Temperature Devices in the Thermal Operating Conditions (see Table 30-2). Removed Note 4 from the DC Temperature and Voltage Specifications (see Table 30-4). Updated all typical and maximum Operating Current (I_{DD}) values (see Table 30-5). Updated all typical and maximum Idle Current (I_{IDLE}) values (see Table 30-6). Updated the maximum Power-Down Current (I_{PD}) values for parameters DC60d, DC60a, and DC60b (see Table 30-7). Updated all typical Doze Current (Idoze) values (see Table 30-8). Updated the maximum value for parameter DI19 and added parameters DI28, DI29, DI60a, DI60b, and DI60c to the I/O Pin Input Specifications (see Table 30-9). Removed Note 2 from the AC Characteristics: Internal RC Accuracy (see Table 30-18). Added Note 2 to the PLL Clock Timing Specifications (see Table 30-17) Updated the Internal RC Accuracy minimum and maximum values for parameter F21b (see Table 30-19). Updated the characteristic description for parameter DI35 in the I/O Timing Requirements (see Table 30-20). Updated *all* SPI specifications (see Table 30-28 through Table 30-35 and Figure 30-9 through Figure 30-16) Updated the ADC Module Specification minimum values for parameters AD05 and AD07, and updated the maximum value for parameter AD06 (see Table 30-41). Updated the ADC Module Specifications (12-bit Mode) minimum and maximum values for parameter AD21a (see Table 30-42). Updated all ADC Module Specifications (10-bit Mode) values, with the exception of Dynamic Performance (see Table 30-43). Updated the minimum value for parameter PM6 and the maximum value for parameter PM7 in the Parallel Master Port Read Timing Requirements (see Table 30-52). Added DMA Read/Write Timing Requirements (see Table 30-54).